

Software Communication Characterization for HPC workload with Intel SW tools – HPC requirements for QDS (Quantum Device Simulation)

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## Outline:

#### **I. QDS General Introduction**

- 1. Target application
- 2. Goal
- **II. Projected Requirements**
- **III. Understand QDS: FP and data parallel** 
  - 1. Capture details of communication profile with ITAC
  - 2. Intel MPI 5.0 (with new MPI 3.0)



### I. QDS Introduction:

- 1. Target application is NEMO-5/Omen
  - provides quantum device simulation
  - key new capability is modeling of scattering
- 2. Goal (Device Modeling Grand Challenge)
  - New ability to simulate 5 nm channel transistor with quantum transport + scattering
    - Present simulations are adequate using 3nm and with quantum transport (ballistic) and no enhanced scattering model
  - turnaround time of 1 week for an IV curve
  - Implement by Q1 2015





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teration each transport inside scattering iterations



#### **II. Projected Requirements**

- 1. Require as many cores as can be provided
  - Target for 32K IVB/HSW core, Memory = 9GB/core
  - Memory requirement per core is a challenge for Xeon Phi
    - It is possible to split computation across multiple cores to reduce memory
- 2. Message passing
  - dominated by regular pattern of large messages
  - for target problem, message size = 40 MB
  - each MPI rank sends the same 40 MB to about 60 other ranks for each energy calculation
  - message size increases with physical problem size
  - message count is constant with physical problem size
- 3. I/O is negligible
- 4. Reliability: must run 32K cores for a week without any crashes



Message pattern summary

- message pattern is very regular
- each MPI rank typically sends an array to about 60 other ranks
- array size depends linearly on physical problem size (number of atoms)
  - e.g., small 3x3x20 wire: 16 MB arrays
  - for target 5x5x20 wire: 40 MB arrays





Message size scales linearly with physical problem size

- target device: message size = 40 MB
- If 60 messages are in flight for a single MPI rank:
  - target device total volume = 2.4 GB

Multiple cores per energy can be used to scale message size down





The *number* of messages sent is independent of physical device size

Fundamental computation is for one energy

- typically 500 energies are calculated in parallel on each inner iteration
- each energy can be computed on one more cores or a core can calculate multiple energies
- each energy depends on messages from typically 60 other energy calculations



Message bandwidth per MPI rank will be:

- bandwidth = 60 \* (message size) / (message time)
- CPU time grows faster than message size
- simplistic bandwidth: assume message time = cpu time





Bandwidth per Node (assuming 20 MPI ranks / node)





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